

MBR230LSF

Surface Mount Schottky Barrier Rectifier
Reverse Voltage :30 V / Forward Current: 2.0A

Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

PINNING

PIN	DESCRIPTION				
1	Cathode				
2	Anode				



Absolute Maximum Ratings and Electrical characteristics Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	MBR230LSF	Units
Maximum Repetitive Peak Reverse Voltage	VRRM	30	
Maximum RMS voltage	V _{RMS}	28	V
Maximum DC Blocking Voltage	V _{pc}	40	V
Maximum Average Forward Rectified Current	I _{F(AV)}	2.0	А
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	50	А
Max Instantaneous Forward Voltage at 2 A	V _F	0.55	V
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a =100°C	I _R	0.5 10	mA
Typical Junction Capacitance 1)	C,	220	pF
Operating Junction Temperature Range	T _j	-55 ~ +125	°C
Storage Temperature Range	T _{stg}	-55 ~ +150	°C

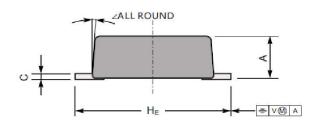
1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

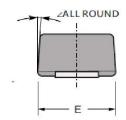


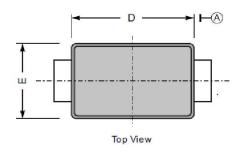


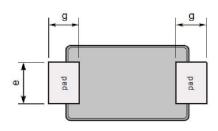
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads





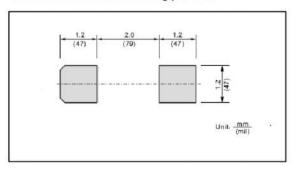




Bottom View

UNIT		Α	С	D	E	е	g	HE	2
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

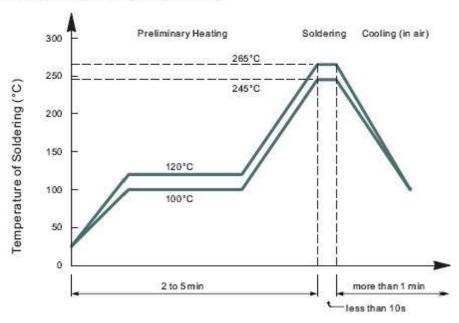
The recommended mounting pad size



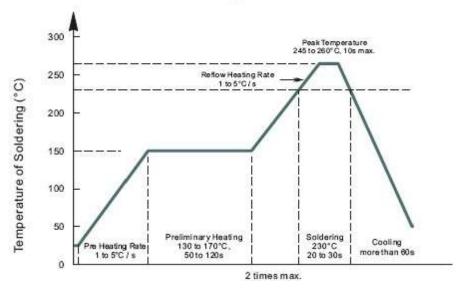
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· Recommended condition of flow soldering



· Recommended condition of reflow soldering



Recommended peak temperature is over 245°C, If peak temperature is below 245°C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)

• Condition of hand soldering: Temperature: 350°C Time: 3s max. Times: one time

• Remark: Lead free solder paste (96.5Sn/3.0Ag/0.5Cu)

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单击下面可查看定价,库存,交付和生命周期等信息

>>SHIKUES(时科)